LITEON®
OPTOELECTRONICS

Through Hole Lamp

Product Data Sheet

LTL1BEKGFJ

Spec No.: DS20-2005-237

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Revision: A

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4

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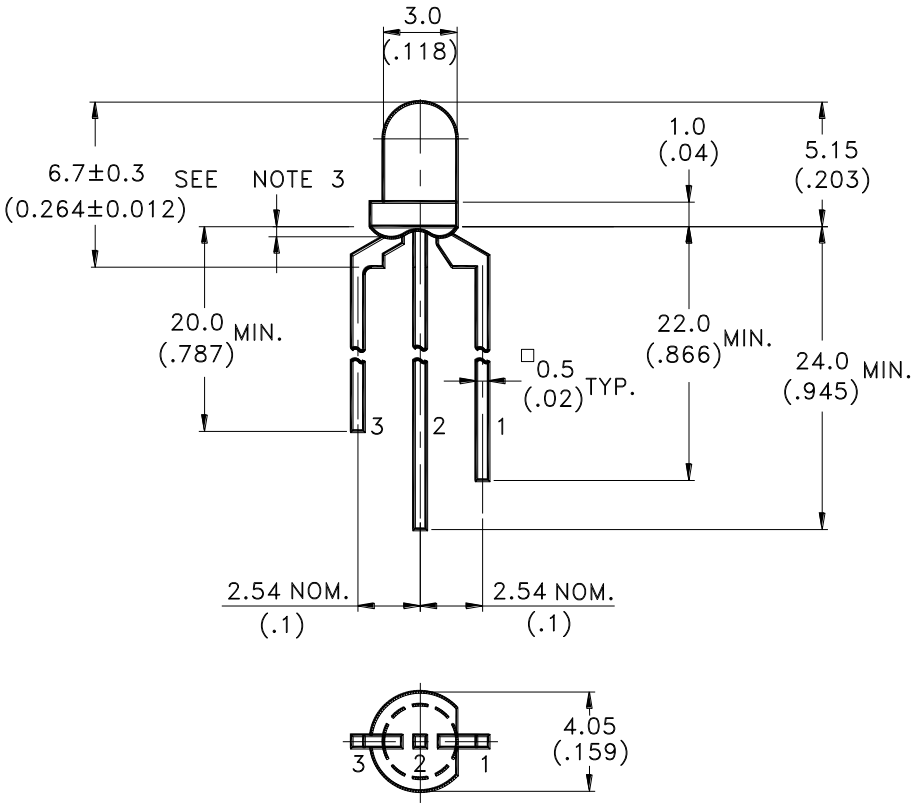
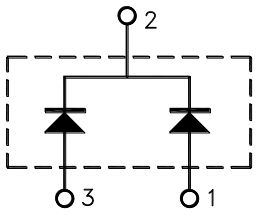
Features

* Lead (Pb) free product and RoHS compliant.
* Amber and Green chips are matched for uniform light output.
* Low power consumption.
* High efficiency.
* Versatile mounting on P.C. board or panel.
* I.C. Compatible/low current requirements.

Package Dimensions





1. Amber Anode
2. Common Cathode
3. Green Anode

Part No.	Lens	Source Color
LTL1BEKGFJ	White Diffused	AlInGaP Green / AlInGaP Amber

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25mm(.010") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specification is subject to change without notice.

Absolute Maximum Ratings at T_A=25℃

Parameter	Green	Amber	Unit
Power Dissipation	75	75	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	60	60	mA
DC Forward Current	30	30	mA
Derating Linear From 30℃	0.4	0.4	mA/℃
Operating Temperature Range	-40℃ to + 100℃		
Storage Temperature Range	-55℃ to + 100℃		
Lead Soldering Temperature [2mm(.08") From Body]	260℃ for 5 Seconds Max		

Electrical Optical Characteristics at T_A=25℃

Parameter	Symbol	Color	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	Iv	Green Amber	65 110	140 240	180 310	mcd	I_F = 20mA I_F = 20mA Note 1,4
Viewing Angle	$2\theta_{1/2}$	Green Amber		60 60		deg	Note 2 (Fig.6)
Peak Emission	λp	Green Amber		575 611		nm	Measurement @Peak (Fig.1)
Dominant Wavelength	λd	Green Amber		572 605		nm	Note 3
Spectral Line Half-Width	Δλ	Green Amber		11 17		nm	
Forward Voltage	V_F	Green Amber		2.1 2.05	2.4 2.4	V	I_F = 20mA
Reverse Current	I_R	Green Amber			100	μA	Note 5 V_R = 5V

Note: 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclairage) eye-response curve.

2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

3. The dominant wavelength, λ_d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

4. The Iv guarantee should be added ±15%.

5. Reverse Voltage (V_R) condition is applied for IR test only. The device is not designed for reverse operation.

Typical Electrical / Optical Characteristics Curves

(25℃ Ambient Temperature Unless Otherwise Noted)

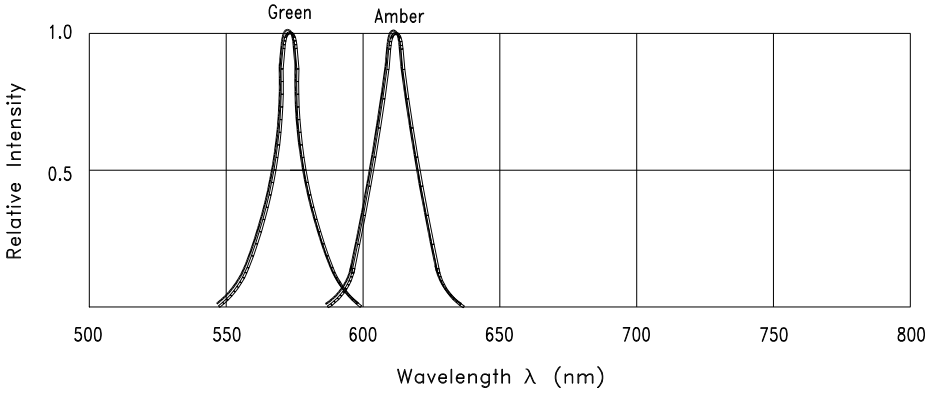


Fig.1 Relative Intensity vs. Wavelength

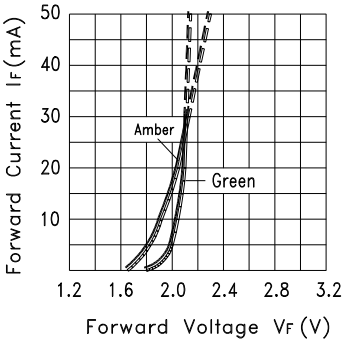


Fig.2 Forward Current vs. Forward Voltage

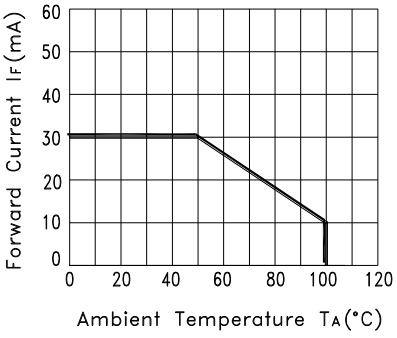


Fig.3 Forward Current Derating Curve

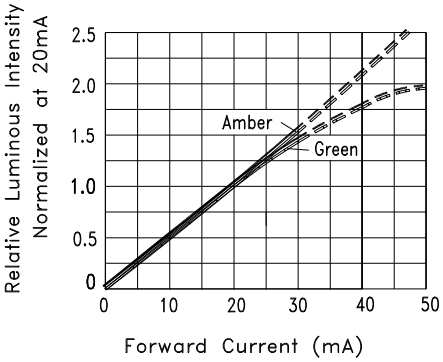


Fig.4 Relative Luminous Intensity vs. Forward Current

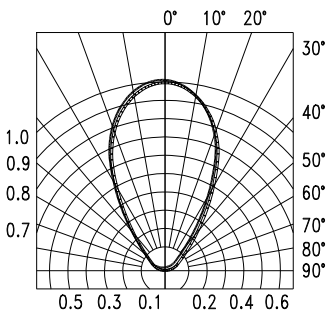
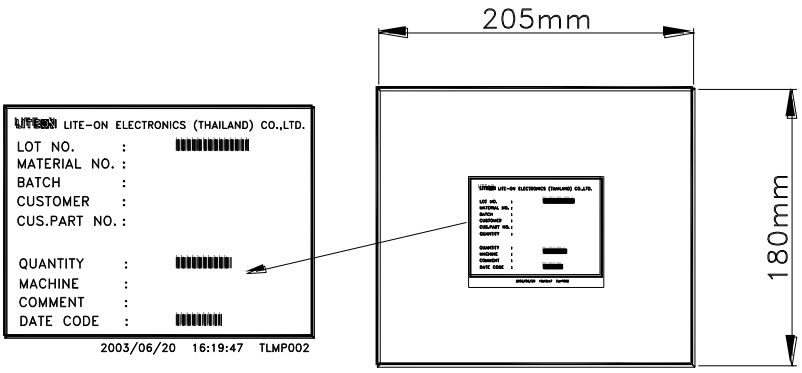


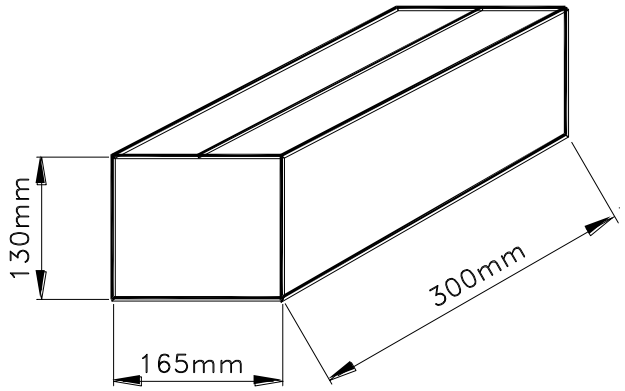
Fig.5 Spatial Distribution

Packing Spec

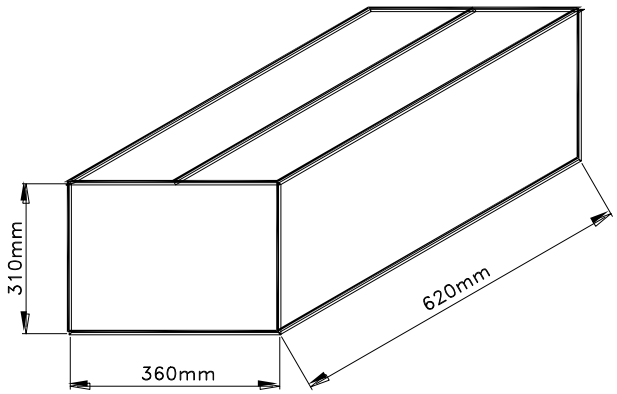
500 or 200, 100 pcs per packing bag



10packing bags per inner carton
total 5,000 pcs per inner carton



8 Inner cartons per outer carton
total 40,000 pcs per outer carton
In every shipping lot, only the last pack will be non-full packing



Bin Table Specification

Luminous Intensity Unit : mcd @20mA					
Box	**Iv Bin Code**	**GREEN Min**	**GREEN Max**	**AMBER Min**	**AMBER Max**
1	DF	65	85	110	140
2	DG	65	85	140	180
3	DH	65	85	180	240
4	DJ	65	85	240	310
5	EF	85	110	110	140
6	EG	85	110	140	180
7	EH	85	110	180	240
8	EJ	85	110	240	310
9	FF	110	140	110	140
10	FG	110	140	140	180
11	FH	110	140	180	240
12	FJ	110	140	240	310
13	GF	140	180	110	140
14	GG	140	180	140	180
15	GH	140	180	180	240
16	GJ	140	180	240	310

Note:

1.0 Tolerance of each bin limit is ±15%

2.0 Tolerance of each bin limit is ±1nm

CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications).Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity.
It is recommended that LEDs out of their original packaging are used within three months.
For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary.

4. Lead Forming & Assembly

During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens.

Do not use the base of the lead frame as a fulcrum during forming.

Lead forming must be done before soldering, at normal temperature.

During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical stress.

5. Soldering

When soldering, leave a minimum of 2mm clearance from the base of the lens to the soldering point.
Dipping the lens into the solder must be avoided.
Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions :

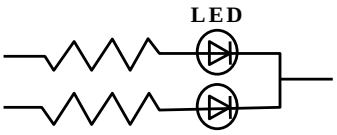
Soldering iron		Wave soldering	
Temperature Soldering time	350℃ Max. 3 sec. Max. (one time only)	Pre-heat Pre-heat time Solder wave Soldering time	100℃ Max. 60 sec. Max. 260℃ Max. 5 sec. Max.

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED. IR reflow is not suitable process for through hole type LED lamp product.

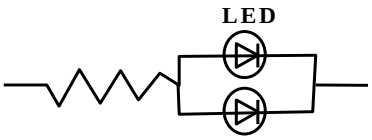
6. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A



Circuit model B



(A) Recommended circuit

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs

7. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use a conductive wrist band or anti- electrostatic glove when handling these LEDs
- All devices, equipment, and machinery must be properly grounded
- Work tables, storage racks, etc. should be properly grounded
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing

Suggested checking list :

Training and Certification

1. Everyone working in a static-safe area is ESD-certified?
2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

1. Static-safe workstation or work-areas have ESD signs?
2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
3. All ionizer activated, positioned towards the units?
4. Each work surface mats grounding is good?

Personnel Grounding

1. Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
2. If conductive footwear used, conductive flooring also present where operator stand or walk?
3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DSL?
5. All wrist strap or heel strap checkers calibration up to date?

Note: *50V for Blue LED.

Device Handling

1. Every ESDS items identified by EIA-471 labels on item or packaging?
2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

Others

1. Audit result reported to entity ESD control coordinator?
2. Corrective action from previous audits completed?
3. Are audit records complete and on file?

8. Reliability Test

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS	MIL-STD-750D:1026 (1995) MIL-STD-883D:1005 (1991) JIS C 7021:B-1 (1982)
	High Temperature High Humidity Storage	Ta= 65±5°C RH= 90 ～ 95% Test Time= 240HRS	MIL-STD-202F: 103B(1980) JIS C 7021 : B-11(1982)
	High Temperature Storage	Ta= 105±5°C *Test Time= 1000HRS	MIL-STD-883D:1008 (1991) JIS C 7021:B-10 (1982)
	Low Temperature Storage	Ta= -55±5°C *Test Time=1000HRS	JIS C 7021:B-12 (1982)
Environmental Test	Temperature Cycling	105°C ～ 25°C ～ -55°C ～ 25°C 30mins 5mins 30mins 5mins 10 Cycles	MIL-STD-202F:107D (1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1010 (1991) JIS C 7021: A-4(1982)
	Thermal Shock	105 ± 5°C ～ -55°C ± 5°C 10mins 10mins 10 Cycles	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011 (1991)
	Solder Resistance	T.sol = 260 °C Max Dwell Time= 5 secs Max	MIL-STD-202F:210A(1980) MIL-STD-750D:2031(1995) JIS C 7021: A-1(1982)
	Solderability	T. sol = 230 ± 5°C Dwell Time= 5 ± 1secs	MIL-STD-202F:208D(1980) MIL-STD-750D:2026(1995) MIL-STD-883D:2003(1991) JIS C 7021: A-2(1982)

9. Others

The appearance and specifications of the product may be modified for improvement, without prior notice.